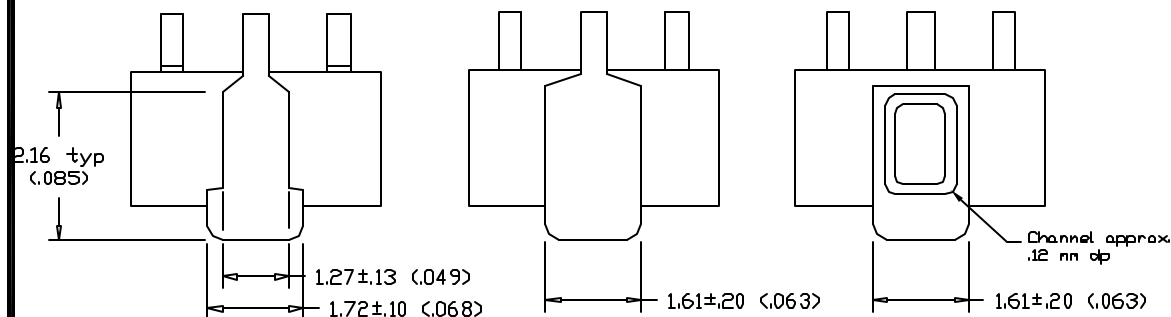
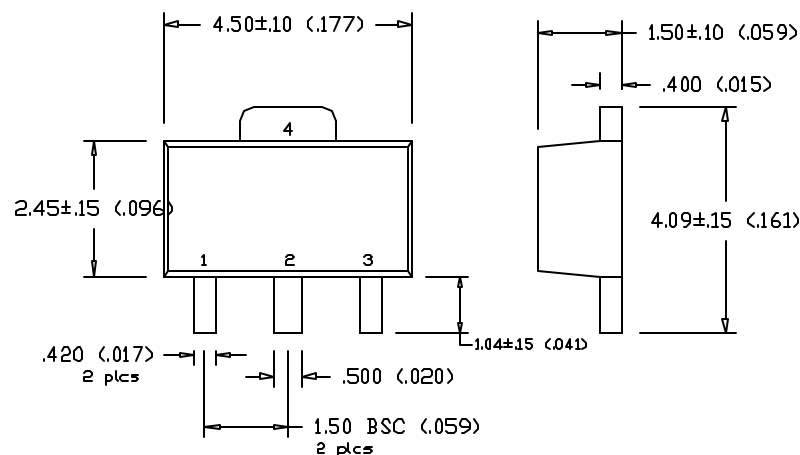




Alternate Backside Patterns
(May be supplied with any pattern shown.)

UNLESS OTHERWISE SPECIFIED,
DIMENSIONS ARE IN mm (inches)
PER ANSI Y14.5M-1982.
TOLERANCES ARE:
DECIMAL ANGLE
.XX ±.12 (.005) ±1/2°
.XXX ±.05 (.002)

MATERIALS:

See Notes

FINISH:

See Notes

Notes:

Base Metal - Copper Dln 194

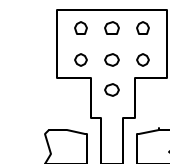
Lead Finish

Basic PN - Sn/Pb Sn =>80%

Z option - 100% Matte Sn - .01 (.0004) thk min

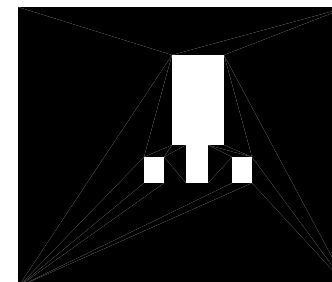
- Do Not Scale Hardcopy -

Caution: The Land Patterns and Solder Mask shown are generic for this package. Refer to product data sheet for any required variations specific to an application.



Scale 4:1

- Generic Land Pattern -
This land pattern is applicable to
both backside patterns shown.



Scale 4:1

- Generic Solder Mask Opening -
This solder mask is applicable to
both backside patterns shown.



Package Type:

SOT-89 4 Ld

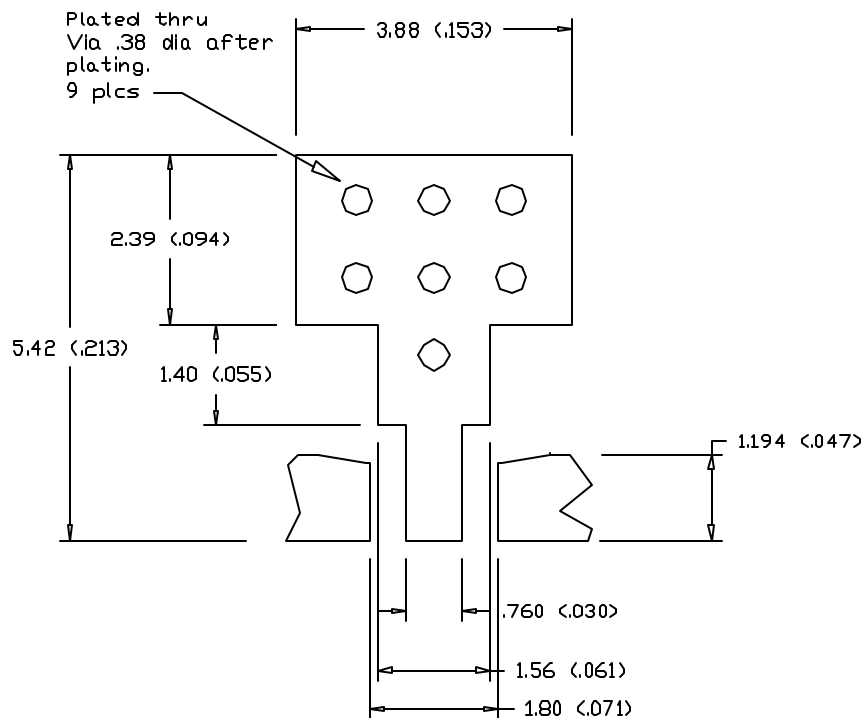
SMDI Package Type: XXX-XX89

Dwg No.

MPO-100136

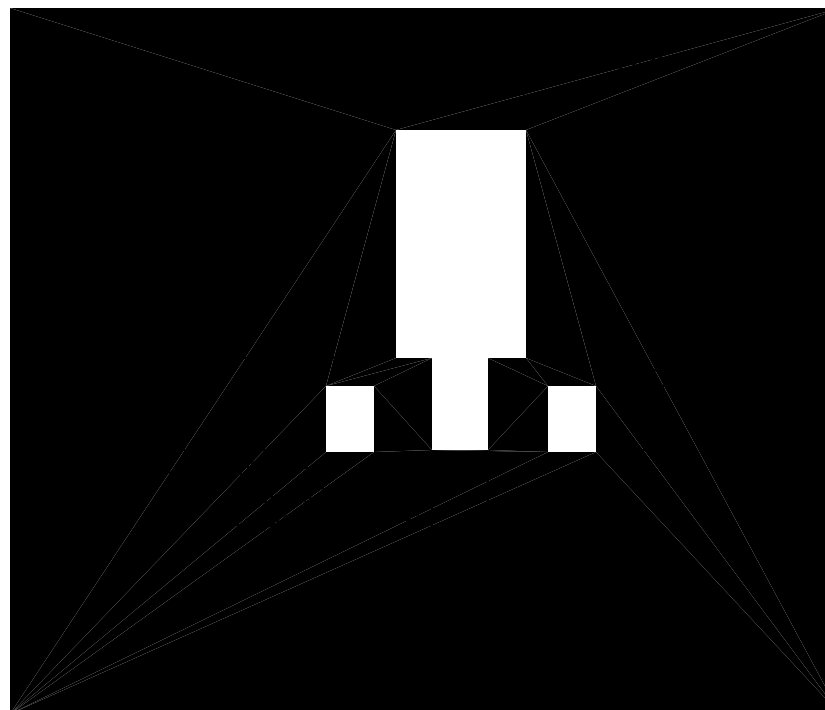
Sht
1 of 2

REV
J



Scale 10:1

- Generic Land Pattern -
This land pattern is applicable to
both backside patterns shown.



Scale 10:1

- Generic Solder Mask Opening -
This solder mask is applicable to
both backside patterns shown.

- Do Not Scale Hardcopy -

SIRENZA MICRODEVICES		
Package Type: SOT-89 4 Ld		
SMDI Package Type: XXX-XX89		
Dwg No. MPO-100136	Sht 2 of 2	REV J